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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	Z8S180
Number of Cores/Bus Width	1 Core, 8-Bit
Speed	10MHz
Co-Processors/DSP	-
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8s18010vsg

GENERAL DESCRIPTION (Continued)

Power connections follow the conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

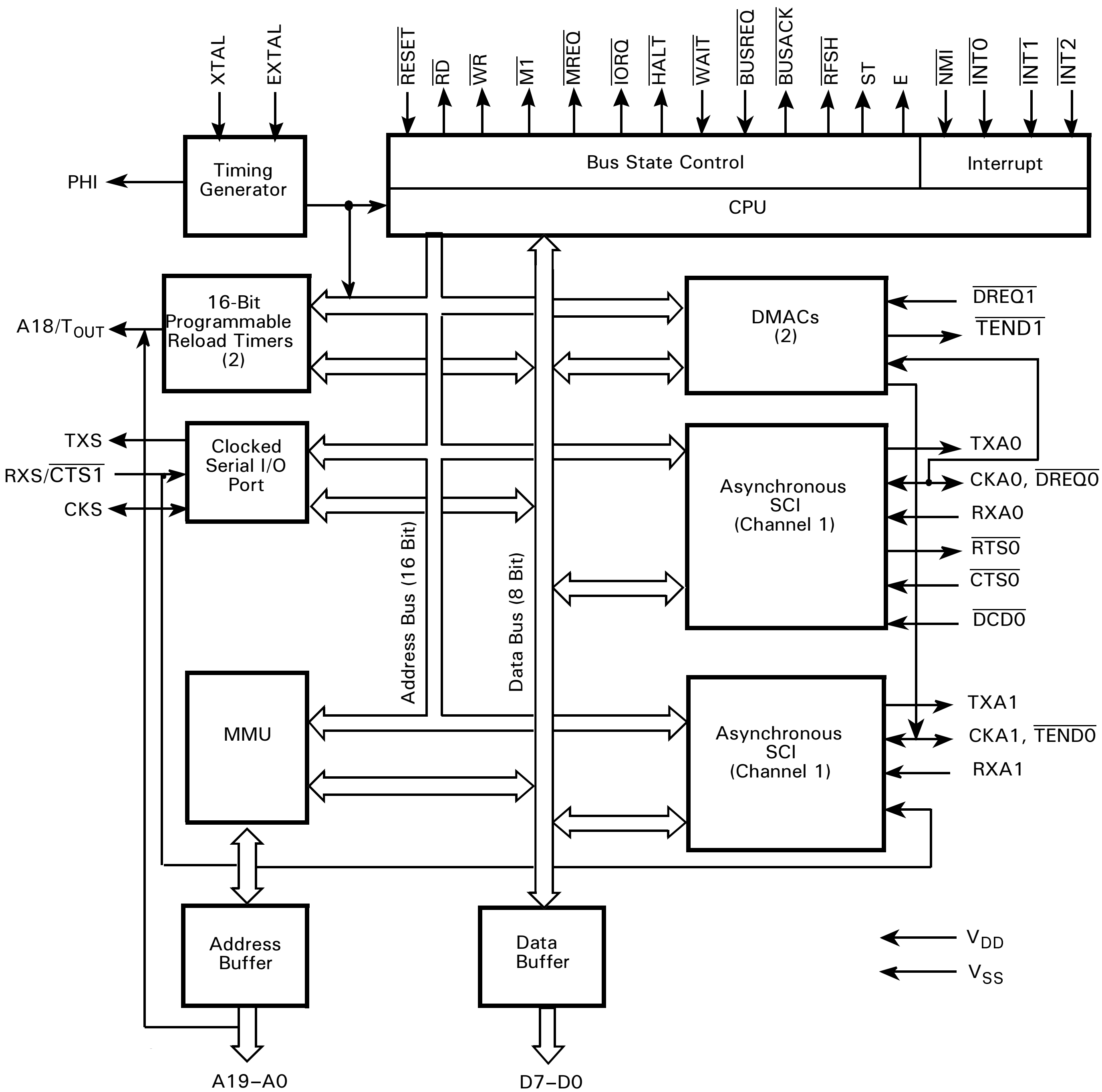


Figure 1. Z8S180/Z8L180 Functional Block Diagram

PIN IDENTIFICATION (Continued)

Table 1. Z8S180/Z8L180 Pin Identification (Continued)

Pin Number and Package Type QFP	PLCC	DIP	Default Function	Secondary Function	Control
13	19	17	A4		
14			NC		
15	20	18	A5		
16	21	19	A6		
17	22	20	A7		
18	23	21	A8		
19	24	22	A9		
20	25	23	A10		
21	26	24	A11		
22			NC		
23			NC		
24	27	25	A12		
25	28	26	A13		
26	29	27	A14		
27	30	28	A15		
28	31	29	A16		
29	32	30	A17		
30			NC		
31	33	31	A18	T_{OUT}	Bit 2 or Bit 3 of TCR
32	34	32	V_{DD}		
33	35		A19		
34	36	33	V_{SS}		
35	37	34	D0		
36	38	35	D1		
37	39	36	D2		
38	40	37	D3		
39	41	38	D4		
40	42	39	D5		
41	43	40	D6		
42			NC		
43			NC		
44	44	41	D7		
45	45	42	$\overline{RTS0}$		
46	46	43	$\overline{CTS0}$		
47	47	44	$\overline{DCD0}$		
48	48	45	TXA0		
49	49	46	RXA0		
50	50	47	CKA0	$\overline{DREQ0}$	Bit 3 or Bit 5 of DMODE
51			NC		
52	51	48	TXA1		

Table 2. Pin Status During RESET, BUSACK, and SLEEP Modes (Continued)

Pin Number and Package Type					Pin Status		
QFP	PLCC	DIP	Default Function	Secondary Function	RESET	BUSACK	SLEEP
39	41	38	D4		3T	3T	3T
40	42	39	D5		3T	3T	3T
41	43	40	D6		3T	3T	3T
42			NC				
43			NC				
44	44	41	D7		3T	3T	3T
45	45	42	$\overline{RTS0}$		High	OUT	High
46	46	43	$\overline{CTS0}$		IN	OUT	IN
47	47	44	$\overline{DCD0}$		IN	IN	IN
48	48	45	TXA0		High	OUT	OUT
49	49	46	RXA0		IN	IN	IN
50	50	47	CKA0		3T	I/O	I/O
			$\overline{DREQ0}$		N/A	IN	IN
51			NC				
52	51	48	TXA1		High	OUT	OUT
53	52		TEST				
54	53	49	RXA1		IN	IN	IN
55	54	50	CKA1		3T	I/O	I/O
			$\overline{TEND0}$		N/A	High	High
56	55	51	TXS		High	OUT	OUT
57	56	52	RXS		IN	IN	IN
			$\overline{CTS1}$		N/A	IN	IN
58	57	53	CKS		3T	I/O	I/O
59	58	54	$\overline{DREQ1}$		IN	3T	IN
60	59	55	$\overline{TEND1}$		High	OUT	High
61	60	56	$\overline{HALT}$		High	High	Low
62			NC				
63			NC				
64	61	57	$\overline{RFSH}$		High	OUT	High
65	62	58	$\overline{IORQ}$		High	3T	High
66	63	59	$\overline{MREQ}$		High	3T	High
67	64	60	E		Low	OUT	OUT
68	65	61	$\overline{M1}$		High	High	High
69	66	62	$\overline{WR}$		High	3T	High
70	67	63	$\overline{RD}$		High	3T	High
71	68	64	PHI		OUT	OUT	OUT
72	1	1	V_{SS}		GND	GND	GND
73	2		V_{SS}		GND	GND	GND
74	3	2	XTAL		OUT	OUT	OUT
75			NC				

PIN DESCRIPTIONS

A0–A19. Address Bus (Output, 3-state). A0–A19 form a 20-bit address bus. The Address Bus provides the address for memory data bus exchanges (up to 1 MB) and I/O data bus exchanges (up to 64 KB). The address bus enters a high–impedance state during reset and external bus acknowledge cycles. Address line A18 is multiplexed with the output of PRT channel 1 (T_{OUT}, selected as address output on reset), and address line A19 is not available in DIP versions of the Z8S180.

BUSACK. Bus Acknowledge (Output, active Low). BUSACK indicates that the requesting device, the MPU address and data bus, and some control signals enter their high-impedance state.

BUSREQ. Bus Request (Input, active Low). This input is used by external devices (such as DMA controllers) to request access to the system bus. This request demands a higher priority than NMI and is always recognized at the end of the current machine cycle. This signal stops the CPU from executing further instructions, places addresses, data buses, and other control signals into the high-impedance state.

CKA0, CKA1. Asynchronous Clock 0 and 1 (bidirectional). When in output mode, these pins are the transmit and receive clock outputs from the ASCI baud rate generators. When in input mode, these pins serve as the external clock inputs for the ASCI baud rate generators. CKA0 is multiplexed with DREQ0, and CKA1 is multiplexed with TEND0.

CKS. Serial Clock (bidirectional). This line is the clock for the CSI/O channel.

CTS0–CTS1. Clear to send 0 and 1 (Inputs, active Low). These lines are modem control signals for the ASCI channels. CTS1 is multiplexed with RXS.

D0–D7. Data Bus = (bidirectional, 3-state). D0–D7 constitute an 8-bit bidirectional data bus, used for the transfer of information to and from I/O and memory devices. The data bus enters the high-impedance state during reset and external bus acknowledge cycles.

DCD0. Data Carrier Detect 0 (Input, active Low); a programmable modem control signal for ASCI channel 0.

DREQ0, DREQ1. DMA Request 0 and 1 (Input, active Low). DREQ is used to request a DMA transfer from one of the on-chip DMA channels. The DMA channels monitor these inputs to determine when an external device is ready for a READ or WRITE operation. These inputs can be programmed to be either level or edge sensed. DREQ0 is multiplexed with CKA0.

E. Enable Clock (Output). This pin functions as a synchronous, machine-cycle clock output during bus transactions.

EXTAL. External Clock Crystal (Input). Crystal oscillator connections. An external clock can be input to the Z8S180/Z8L180 on this pin when a crystal is not used. This input is Schmitt triggered.

HALT. HALT/SLEEP (Output, active Low). This output is asserted after the CPU executes either the HALT or SLEEP instruction and is waiting for either a nonmaskable or a maskable interrupt before operation can resume. It is also used with the M1 and ST signals to decode the status of the CPU machine cycle.

INT0. Maskable Interrupt Request 0 (Input, active Low). This signal is generated by external I/O devices. The CPU honors these requests at the end of the current instruction cycle as long as the NMI and BUSREQ signals are inactive. The CPU acknowledges this interrupt request with an interrupt acknowledge cycle. During this cycle, both the M1 and IORQ signals become active.

INT1, INT2. Maskable Interrupt Request 1 and 2 (Inputs, active Low). This signal is generated by external I/O devices. The CPU honors these requests at the end of the current instruction cycle as long as the NMI, BUSREQ, and INT0 signals are inactive. The CPU acknowledges these requests with an interrupt acknowledge cycle. Unlike the acknowledgment for INT0, neither the M1 or IORQ signals become active during this cycle.

IORQ. I/O Request (Output, active Low, 3-state). IORQ indicates that the address bus contains a valid I/O address for an I/O READ or I/O WRITE operation. IORQ is also generated, along with M1, during the acknowledgment of the INT0 input signal to indicate that an interrupt response vector can be place onto the data bus. This signal is analogous to the IOE signal of the Z64180.

M1. Machine Cycle 1 (Output, active Low). Together with MREQ, M1 indicates that the current cycle is the opcode-fetch cycle of instruction execution. Together with IORQ, M1 indicates that the current cycle is for interrupt acknowledgment. It is also used with the HALT and ST signal to decode the status of the CPU machine cycle. This signal is analogous to the LIR signal of the Z64180.

MREQ. Memory Request (Output, active Low, 3-state). MREQ indicates that the address bus holds a valid address for a memory READ or memory WRITE operation. This signal is analogous to the ME signal of Z64180.

NMI. Nonmaskable Interrupt (Input, negative edge triggered). NMI demands a higher priority than INT and is al-

OPERATION MODES (Continued)

The Z8S180/Z8L180 leaves HALT mode in response to:

- Low on $\overline{RESET}$
- Interrupt from an enabled on-chip source
- External request on $\overline{NMI}$
- Enabled external request on $\overline{INT0}$, $\overline{INT1}$, or $\overline{INT2}$

In case of an interrupt, the return address is the instruction following the HALT instruction. The program can either branch back to the HALT instruction to wait for another interrupt or can examine the new state of the system/application and respond appropriately.

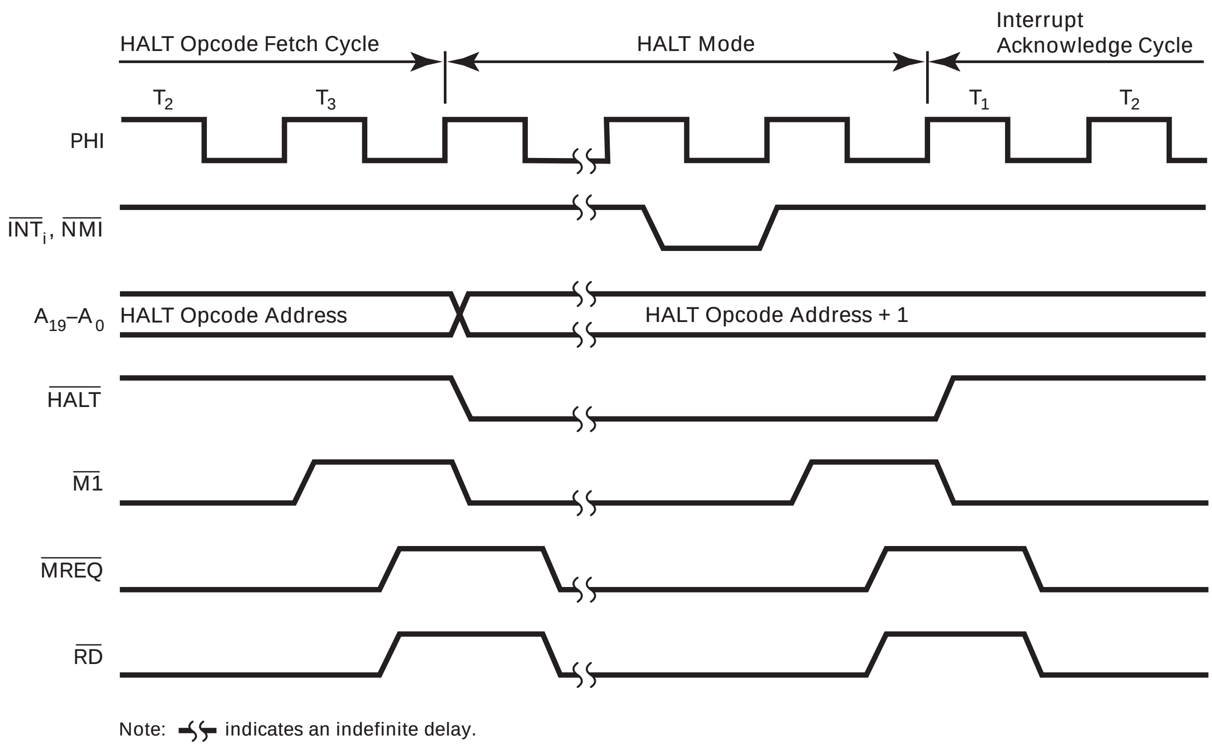


Figure 13. HALT Timing

SLEEP Mode. This mode is entered by keeping the IOSTOP bit (ICR5) and bits 3 and 6 of the CPU Control Register (CCR3, CCR6) all zero and executing the SLP instruction. The oscillator and PHI output continue operating, but are blocked from the CPU core and DMA channels to reduce power consumption. DRAM refresh stops, but interrupts and granting to an external Master can occur. Except when the bus is granted to an external Master, A19–0 and all control signals except $\overline{HALT}$ are maintained High. $\overline{HALT}$ is Low. I/O operations continue as before the SLP instruction, except for the DMA channels.

The Z8S180/Z8L180 leaves SLEEP mode in response to a Low on $\overline{RESET}$, an interrupt request from an on-chip source, an external request on $\overline{NMI}$, or an external request on $\overline{INT0}$, $\overline{INT1}$, or $\overline{INT2}$.

If an interrupt source is individually disabled, it cannot bring the Z8S180/Z8L180 out of SLEEP mode. If an interrupt source is individually enabled, and the IEF bit is `1` so that interrupts are globally enabled (by an EI instruction), the highest priority active interrupt occurs with the return address being the instruction after the SLP instruction. If an interrupt source is individually enabled, but the IEF bit is `0` so that interrupts are globally disabled (by a DI instruction), the Z8S180/Z8L180 leaves SLEEP mode by simply executing the following instruction(s).

ing the bus to an external Master during STANDBY mode, when the BREXT bit in the CPU Control Register (CCR5) is 1.

As described previously for SLEEP and IDLE modes, when the MPU leaves STANDBY mode due to $\overline{\text{NMI}}$ Low or an enabled $\overline{\text{INT0}}$–$\overline{\text{INT2}}$ Low when the IEF, flag is 1 due to an IE instruction, it starts by performing the interrupt with the return address being that of the instruction following the SLP instruction. If the Z8S180/Z8L180 leaves STANDBY mode due to an external interrupt request that's enabled in the INT/TRAP Control Register, but the IEF, bit is 0 due to a DI instruction, the processor restarts by executing the instruction(s) following the SLP instruction. If $\overline{\text{INT0}}$, or $\overline{\text{INT1}}$ or $\overline{\text{INT2}}$ goes inactive before the end of the clock stabilization delay, the Z8S180/Z8L180 stays in STANDBY mode.

Figure 17 indicates the timing for leaving STANDBY mode due to an interrupt request.

Note: The Z8S180/Z8L180 takes either 64 or 2^{17} (131,072) clocks to restart, depending on the CCR3 bit.

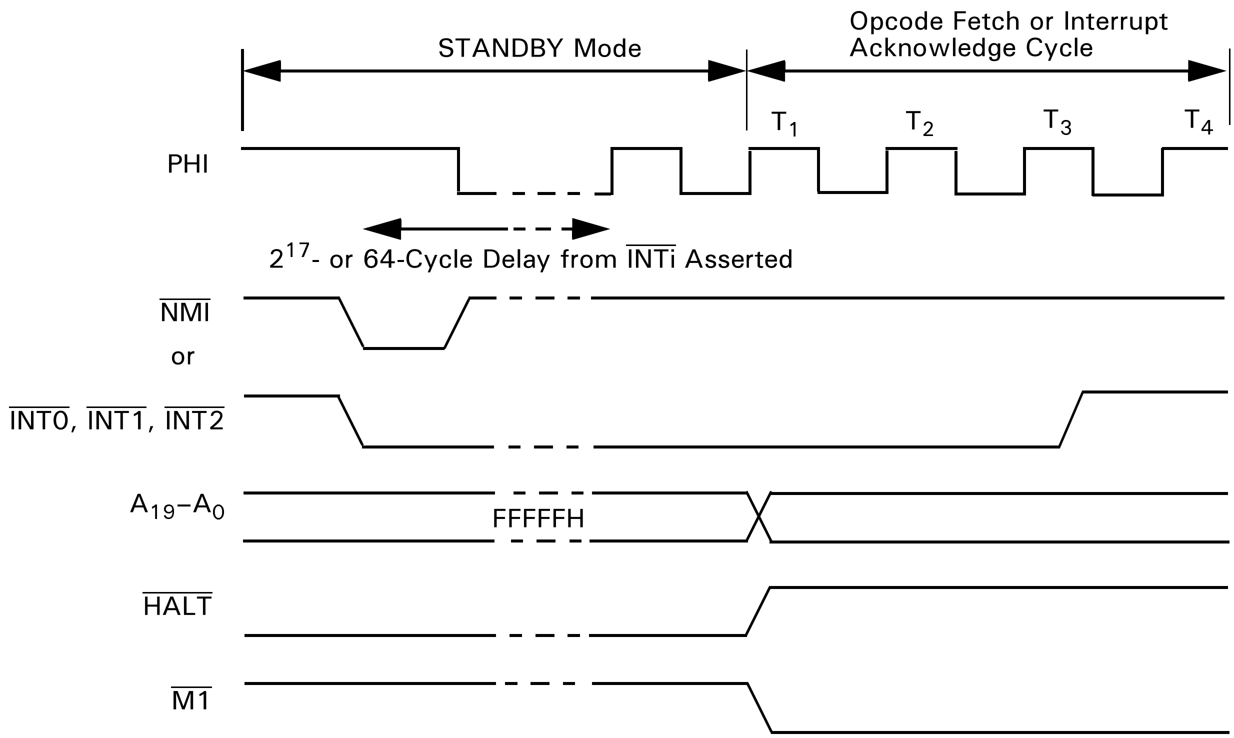


Figure 17. Z8S180/Z8L180 STANDBY Mode Exit Due to External Interrupt

While the Z8S180/Z8L180 is in STANDBY mode, it grants the bus to an external Master if the BREXT bit (CCR5) is 1. Figure 18 indicates the timing of this sequence. The device takes 64 or 2^{17} (131,072) clock cycles to grant the bus depending on the CCR3 bit. The latter (not the QUICK RECOVERY) case may be prohibitive for many demand-driven external Masters. If so, QUICK RECOVERY or IDLE mode can be used.

DC CHARACTERISTICS—Z8S180

Table 6. Z8S180 DC Characteristics
V_{DD} = 5V ±10%; V_{SS} = 0V

Symbol	Item	Condition	Min	Typ	Max	Unit
V_{IH1}	Input H Voltage $\overline{RESET}$, EXTAL, $\overline{NMI}$		V_{DD} –0.6	—	V_{DD} +0.3	V
V_{IH2}	Input H Voltage Except $\overline{RESET}$, EXTAL, $\overline{NMI}$		2.0	—	V_{DD} +0.3	V
V_{IH3}	Input H Voltage CKS, CKA0, CKA1		2.4	—	V_{DD} +0.3	V
V_{IL1}	Input L Voltage RESET, EXTAL, NMI		–0.3	—	0.6	V
V_{IL2}	Input L Voltage Except RESET, EXTAL, NMI		–0.3	—	0.8	V
V_{OH}	Outputs H Voltage All outputs	I_{OH} = –200 µA	2.4	—	—	V
		I_{OH} = –20 µA	V_{DD} –1.2	—	—	
V_{OL}	Outputs L Voltage All outputs	I_{OL} = 2.2 mA	—	—	0.45	V
I_{IL}	Input Leakage Current All Inputs Except XTAL, EXTAL	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{TL}	Three State Leakage Current	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{DD}[1]	Power Dissipation (Normal Operation)	F = 10 MHz	—	25	60	mA
		20		30	50	
		33		60	100	
	Power Dissipation (SYSTEM STOP mode)	F = 10 MHz	—	2	5	
		20		3	6	
		33		5	9	
C_P	Pin Capacitance	V_{IN} = 0_V, f = 1 MHz T_A = 25°C	—	—	12	pF

Note:
1. V_{IHmin} = V_{DD}–1.0V, V_{ILmax} = 0.8V (All output terminals are at NO LOAD.) V_{DD} = 5.0V.

AC CHARACTERISTICS—Z8S180 (Continued)

Table 8. Z8S180 AC Characteristics (Continued)
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
32	t_{INTH}	$\overline{INT}$ Hold Time from PHI Fall	10	—	10	—	ns
33	t_{NMIW}	$\overline{NMI}$ Pulse Width	35	—	25	—	ns
34	t_{BRS}	$\overline{BUSREQ}$ Set-up Time to PHI Fall	10	—	10	—	ns
35	t_{BRH}	$\overline{BUSREQ}$ Hold Time from PHI Fall	10	—	10		ns
36	t_{BAD1}	PHI Rise to $\overline{BUSACK}$ Fall Delay	—	25	—	15	ns
37	t_{BAD2}	PHI Fall to $\overline{BUSACK}$ Rise Delay	—	25	—	15	ns
38	t_{BZD}	PHI Rise to Bus Floating Delay Time	—	40	—	30	ns
39	t_{MEWH}	$\overline{MREQ}$ Pulse Width (High)	35	—	25	—	ns
40	t_{MEWL}	$\overline{MREQ}$ Pulse Width (Low)	35	—	25	—	ns
41	t_{RFD1}	PHI Rise to $\overline{RFSH}$ Fall Delay	—	20	—	15	ns
42	t_{RFD2}	PHI Rise to $\overline{RFSH}$ Rise Delay	—	20	—	15	ns
43	t_{HAD1}	PHI Rise to $\overline{HALT}$ Fall Delay	—	15	—	15	ns
44	t_{HAD2}	PHI Rise to $\overline{HALT}$ Rise Delay	—	15	—	15	ns
45	t_{DRQS}	$\overline{DREQ1}$ Set-up Time to PHI Rise	20	—	15	—	ns
46	t_{DRQH}	$\overline{DREQ1}$ Hold Time from PHI Rise	20	—	15	—	ns
47	t_{TED1}	PHI Fall to $\overline{TENDi}$ Fall Delay	—	25	—	15	ns
48	t_{TED2}	PHI Fall to $\overline{TENDi}$ Rise Delay	—	25	—	15	ns
49	t_{ED1}	PHI Rise to E Rise Delay	—	30	—	15	ns
50	t_{ED2}	PHI Fall or Rise to E Fall Delay	—	30	—	15	ns
51	P_{WEH}	E Pulse Width (High)	25	—	20	—	ns
52	P_{WEL}	E Pulse Width (Low)	50	—	40	—	ns
53	t_{Er}	Enable Rise Time	—	10	—	10	ns
54	t_{Ef}	Enable Fall Time	—	10	—	10	ns
55	t_{TOD}	PHI Fall to Timer Output Delay	—	75	—	50	ns
56	t_{STDI}	CSI/O Transmit Data Delay Time (Internal Clock Operation)	—	2	—	2	tcyc
57	t_{STDE}	CSI/O Transmit Data Delay Time (External Clock Operation)	—	7.5 t_{CYC} +75	—	75 t_{CYC} +60	ns
58	t_{SRSI}	CSI/O Receive Data Set-up Time (Internal Clock Operation)	1	—	1	—	tcyc
59	t_{SRHI}	CSI/O Receive Data Hold Time (Internal Clock Operation)	1	—	1	—	tcyc
60	t_{SRSE}	CSI/O Receive Data Set-up Time (External Clock Operation)	1	—	1	—	tcyc
61	t_{SRHE}	CSI/O Receive Data Hold Time (External Clock Operation)	1	—	1	—	tcyc
62	t_{RES}	$\overline{RESET}$ Set-up Time to PHI Fall	40	—	25	—	ns

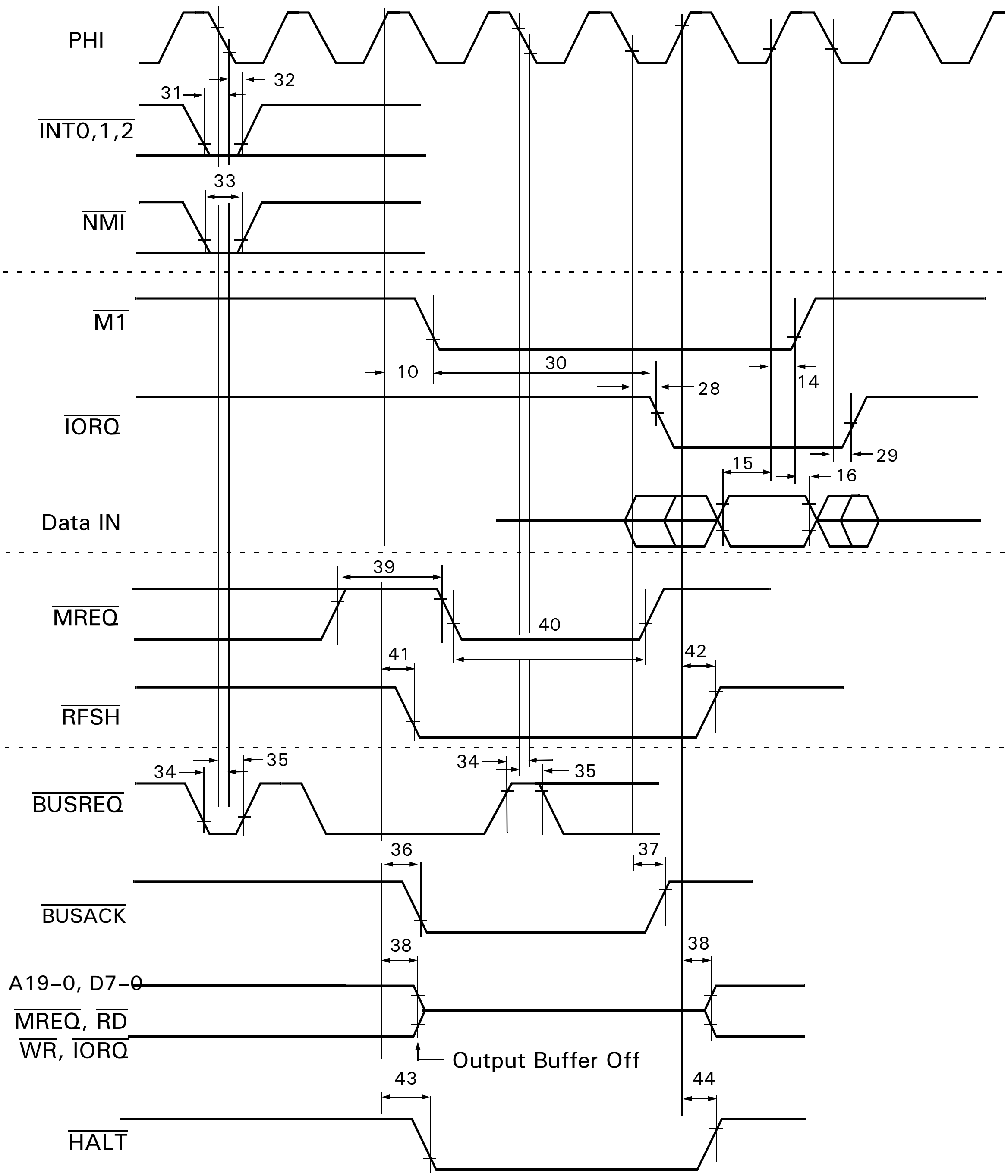


Figure 21. CPU Timing
($\overline{INT0}$ Acknowledge Cycle, Refresh Cycle, BUS RELEASE Mode, HALT Mode, SLEEP Mode, SYSTEM STOP Mode)

TIMING DIAGRAMS (Continued)

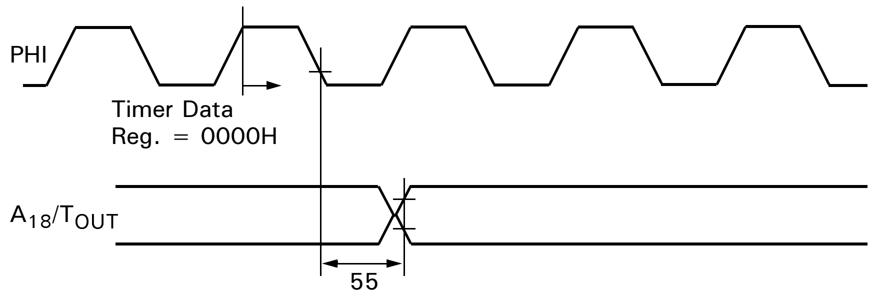


Figure 27. Timer Output Timing

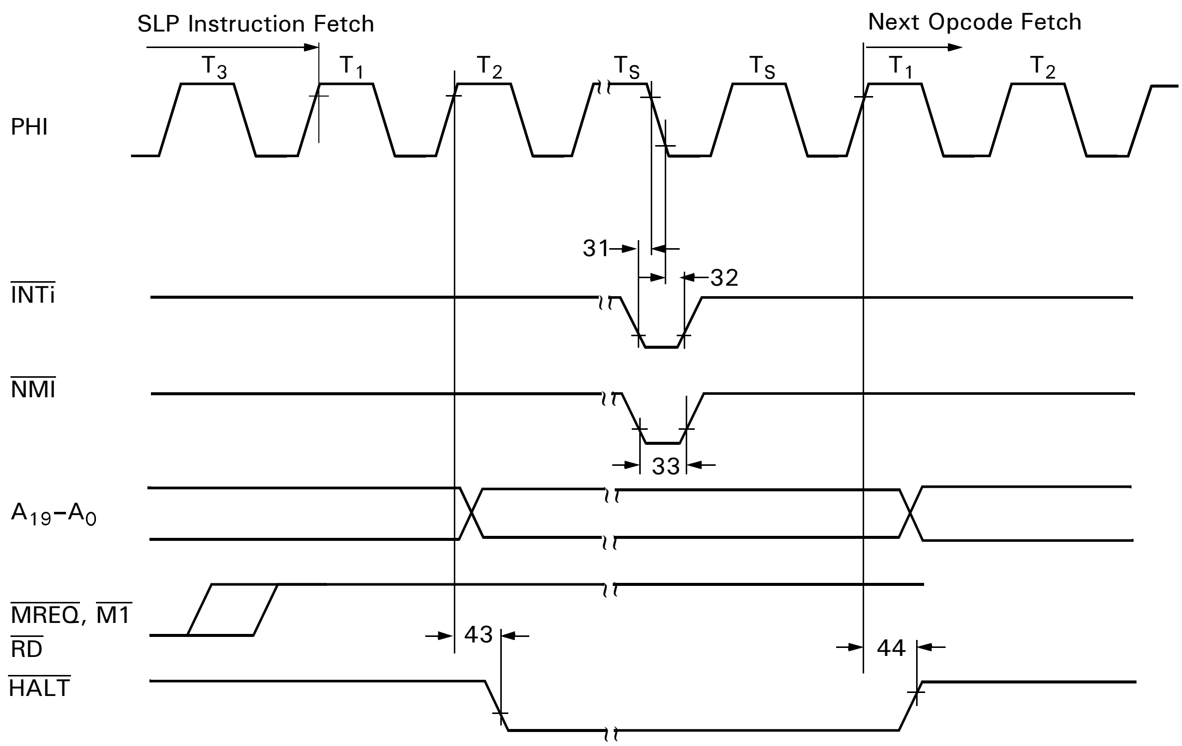


Figure 28. SLP Execution Cycle

CPU CONTROL REGISTER

CPU Control Register (CCR). This register controls the basic clock rate, certain aspects of Power-Down modes, and output drive/low-noise options (Figure 31).

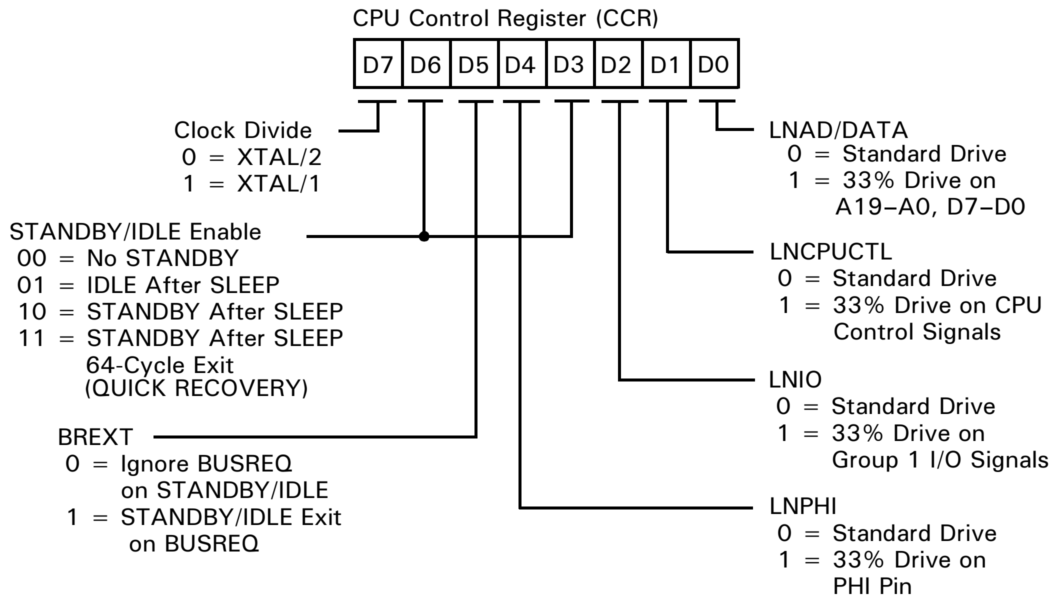


Figure 31. CPU Control Register (CCR) Address 1FH

Bit 7. Clock Divide Select. If this bit is 0, as it is after a RESET, the Z8S180/Z8L180 divides the frequency on the XTAL pin(s) by two to obtain its Master clock PHI. If this bit is programmed as 1, the part uses the XTAL frequency as PHI without division.

If an external oscillator is used in divide-by-one mode, the minimum pulse width requirement provided in the AC Characteristics must be satisfied.

Bits 6 and 3. STANDBY/IDLE Control. When these bits are both 0, a SLP instruction makes the Z8S180/Z8L180 enter SLEEP or SYSTEM STOP mode, depending on the IOSTOP bit (ICR5).

When D6 is 0 and D3 is 1, setting the IOSTOP bit (ICR5) and executing a SLP instruction puts the Z8S180/Z8L180 into IDLE mode in which the on-chip oscillator runs, but its output is blocked from the rest of the part, including PHI out.

When D6 is 1 and D3 is 0, setting IOSTOP (ICR5) and executing a SLP instruction puts the part into STANDBY mode, in which the on-chip oscillator is stopped and the part allows 2^{17} (128K) clock cycles for the oscillator to stabilize when it restarts.

When D6 and D3 are both 1, setting IOSTOP (ICR5) and executing a SLP instruction puts the part into QUICK RECOVERY STANDBY mode, in which the on-chip oscillator is stopped, and the part allows only 64 clock cycles for the oscillator to stabilize when it restarts.

The latter section, HALT and LOW POWER modes, describes the subject more fully.

Bit 5 BREXT. This bit controls the ability of the Z8S180/Z8L180 to honor a bus request during STANDBY mode. If this bit is set to 1 and the part is in STANDBY mode, a BUSREQ is honored after the clock stabilization timer is timed out.

Bit 4 LNPHI. This bit controls the drive capability on the PHI Clock output. If this bit is set to 1, the PHI Clock output is reduced to 33 percent of its drive capability.

ASCI RECEIVE REGISTER

Register addresses 08H and 09H hold the ASCI receive data for channel 0 and channel 1, respectively.

ASCI Receive Register Channel 0

Mnemonic RDR0
Address 08H

7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	–

ASCI Transmit Data

Figure 38. ASCI Receive Register Channel 0

ASCI Receive Register Channel 1

Mnemonic RDR1
Address 09H

7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	–

ASCI Transmit Data

Figure 39. ASCI Receive Register Channel 1

CSI/O CONTROL/STATUS REGISTER

The CSI/O Control/Status Register (CNTR) is used to monitor CSI/O status, enable and disable the CSI/O, enable and disable interrupt generation, and select the data clock speed and source.

Bit	7	6	5	4	3	2	1	0
	EF	EIE	RE	TE	—	SS2	SS1	SS0
	R	R/W	R/W	R/W		R/W	R/W	R/W

Figure 40. CSI/O Control Register (CNTR: I/O Address = 000AH)

EF: End Flag (Bit 7). EF is set to 1 by the CSI/O to indicate completion of an 8-bit data transmit or receive operation. If End Interrupt Enable (EIE) bit = 1 when EF is set to 1, a CPU interrupt request is generated. Program access of TRDR only occurs if EF = 1. The CSI/O clears EF to 0 when TRDR is read or written. EF is cleared to 0 during RESET and IOSTOP mode.

EIE: End Interrupt Enable (Bit 6). EIE is set to 1 to generate a CPU interrupt request. The interrupt request is inhibited if EIE is reset to 0. EIE is cleared to 0 during RESET.

RE: Receive Enable (Bit 5). A CSI/O receive operation is started by setting RE to 1. When RE is set to 1, the data clock is enabled. In internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted in on the RXS pin in synchronization with the (internal or external) data clock. After receiving 8 bits of data, the CSI/O automatically clears RE to 0, EF is set to 1, and an interrupt (if enabled by EIE = 1) is generated. RE and TE are never both set to 1 at the same time. RE is cleared to 0 during RESET and IOSTOP mode.

TE: Transmit Enable (Bit 4). A CSI/O transmit operation is started by setting TE to 1. When TE is set to 1, the data clock is enabled. When in internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted out on the TXS pin synchronous with the (internal or external) data clock. After transmitting 8 bits of data, the CSI/O automatically clears TE to 0, sets EF to 1, and requests an interrupt if enabled by EIE = 1. TE and RE are

DMA BYTE COUNT REGISTER CHANNEL 0

The DMA Byte Count Register Channel 0 specifies the number of bytes to be transferred. This register contains 16 bits and may specify up to 64-KB transfers. When one byte is transferred, the register is decremented by one. If n bytes should be transferred, n must be stored before the DMA operation.

Note: All DMA Count Register channels are undefined during RESET.

DMA Byte Count Register Channel 0 Low

Mnemonic BCR0L
Address 26H

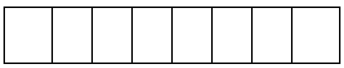


Figure 61. DMA Byte Count Register 0 Low

DMA Byte Count Register Channel 0 High

Mnemonic BCR0H
Address 27H

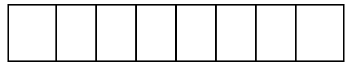


Figure 62. DMA Byte Count Register 0 High

DMA Byte Count Register Channel 1 Low

Mnemonic BCR1L
Address 2EH

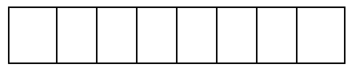


Figure 63. DMA Byte Count Register 1 Low

DMA Byte Count Register Channel 1 High

Mnemonic BCR1H
Address 2FH

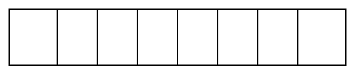


Figure 64. DMA Byte Count Register 1 High

DMA MEMORY ADDRESS REGISTER CHANNEL 1

The DMA Memory Address Register Channel 1 specifies the physical memory address for channel 1 transfers. The address may be a destination or a source memory location. The register contains 20 bits and may specify up to 1024 KB memory addresses.

DMA Memory Address Register, Channel 1L

Mnemonic MAR1L
Address 28H

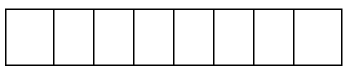


Figure 65. DMA Memory Address Register, Channel 1L

DMA Memory Address Register, Channel 1H

Mnemonic MAR1H
Address 29H

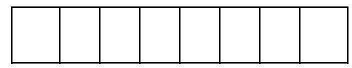


Figure 66. DMA Memory Address Register, Channel 1H

DMA Memory Address Register, Channel 1B

Mnemonic MAR1B
Address 2AH

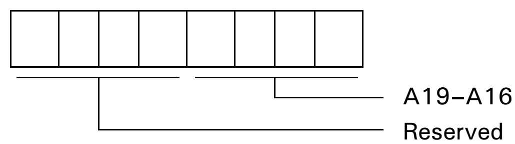


Figure 67. DMA Memory Address Register, Channel 1B

INTERRUPT VECTOR LOW REGISTER

Bits 7–5 of the Interrupt Vector Low Register (I_L) are used as bits 7–5 of the synthesized interrupt vector during interrupts for the $\overline{\text{INT1}}$ and $\overline{\text{INT2}}$ pins and for the DMAs, ASCIs, PRTs, and CSI/O. These three bits are cleared to 0 during RESET (Figure 74).

Interrupt Vector Low Register

Mnemonic: IL
Address 33H

Bit	7	6	5	4	3	2	1	0
	IL 7	IL 6	IL 5	– –	– –	– –	– –	– –
	R/W	R/W	R/W					
	Programmable			Interrupt Source Dependent Code				

Figure 74. Interrupt Vector Low Register (IL: I/O Address = 33H)

INT/TRAP CONTROL REGISTER

This register is used in handling TRAP interrupts and to enable or disable Maskable Interrupt Level 0 and the $\overline{\text{INT1}}$ and $\overline{\text{INT2}}$ pins.

INT/TRAP Control Register

Mnemonics ITC
Address 34H

Bit	7	6	5	4	3	2	1	0
	TRAP	UFO	– –	– –	– –	ITE2	ITE1	ITE0
	R/W	R				R/W	R/W	R/W

TRAP (Bit 7). This bit is set to 1 when an undefined opcode is fetched. TRAP can be reset under program control by writing it with a 0; however, TRAP cannot be written with 1 under program control. TRAP is reset to 0 during RESET.

UFO: Undefined Fetch Object (Bit 6). When a TRAP interrupt occurs, the contents of UFO allow the starting address of the undefined instruction to be determined. This interrupt is necessary because the TRAP may occur on either the second or third byte of the opcode. UFO allows the stacked PC value to be correctly adjusted. If UFO = 0, the first opcode should be interpreted as the stacked PC-1. If UFO = 1, the first opcode address is stacked PC-2. UFO is Read-Only.

ITE2, 1, 0: Interrupt Enable 2, 1, 0 (Bits 2–0). ITE2 and ITE1 enable and disable the external interrupt inputs $\overline{\text{INT2}}$ and $\overline{\text{INT1}}$, respectively. ITE0 enables and disables interrupts from:

- ESCC
- CTCs
- Bidirectional Centronics controller
- External interrupt input $\overline{\text{INT0}}$

A 1 in a bit enables the corresponding interrupt level while a 0 disables it. A RESET sets ITE0 to 1 and clears ITE1 and ITE2 to 0.

TRAP Interrupt. The Z8S180/Z8L180 generates a TRAP sequence when an undefined opcode fetch occurs. This feature can be used to increase software reliability, implement an *extended* instruction set, or both. TRAP may occur during opcode fetch cycles and also if an undefined opcode is fetched during the interrupt acknowledge cycle for $\overline{\text{INT0}}$ when Mode 0 is used.

When a TRAP sequence occurs, the Z8S180/Z8L180:

1. Sets the TRAP bit in the Interrupt TRAP/Control (ITC) register to 1.
2. Saves the current Program Counter (PC) value, reflecting the location of the undefined opcode, on the stack.
3. Resumes execution at logical address 0.

Note: If logical address 0000H is mapped to physical address 00000H, the vector is the same as for RESET. In this case, testing the TRAP bit in ITC reveals whether the restart at physical address 00000H was caused by RESET or TRAP.

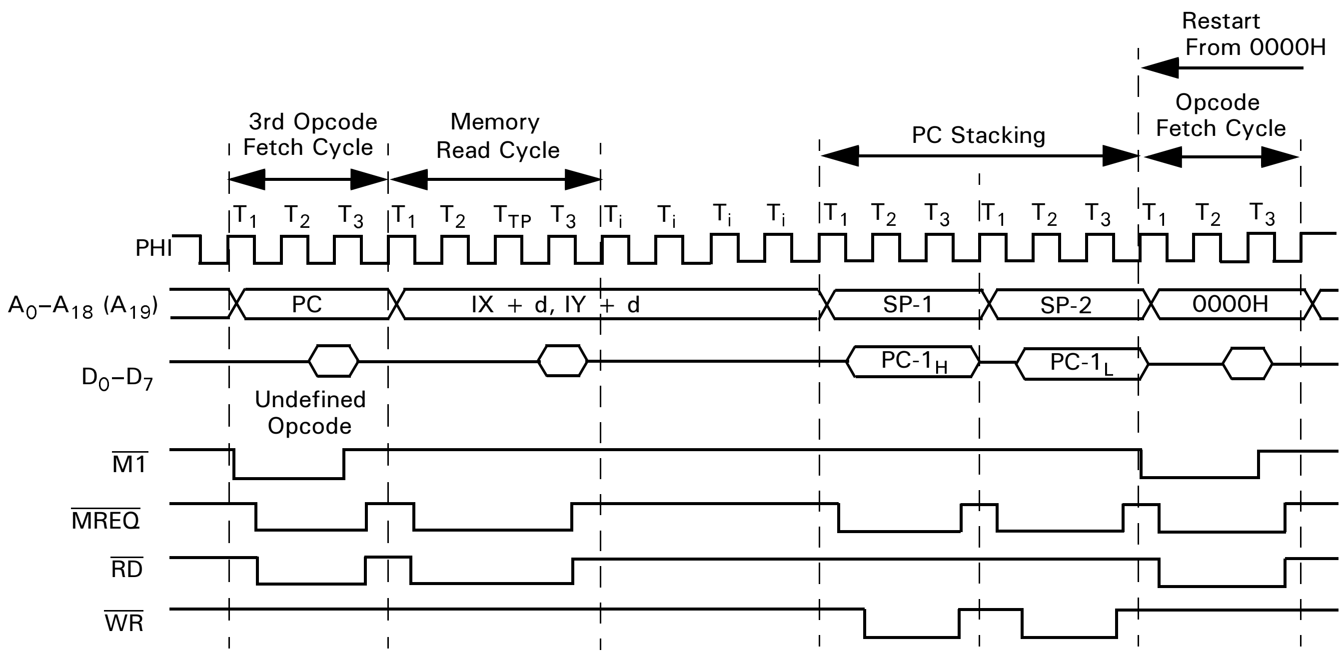


Figure 76. TRAP Timing—3rd Opcode Undefined

REFRESH CONTROL REGISTER

Mnemonic RCR
Address 36H

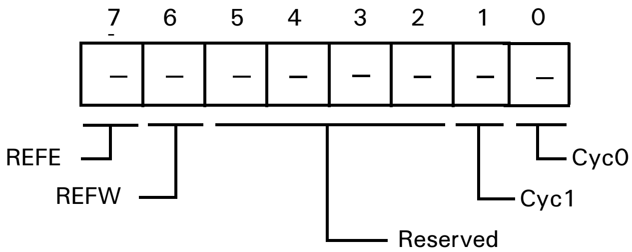


Figure 77. Refresh Control Register (RCR: I/O Address = 36H)

The Refresh Control Register (RCR) specifies the interval and length of refresh cycles, while enabling or disabling the refresh function.

REFE: Refresh Enable (Bit 7). REFE = 0 disables the refresh controller, while REFE = 1 enables refresh cycle insertion. REFE is set to 1 during RESET.

REFW: Refresh Wait (Bit 6). REFW = 0 causes the refresh cycle to be two clocks in duration. REFW = 1 causes the refresh cycle to be three clocks in duration by adding a refresh wait cycle (TRW). REFW is set to 1 during RESET.

CYC1, 0: Cycle Interval (Bit 1,0). CYC1 and CYC0 specify the interval (in clock cycles) between refresh cycles. When dynamic RAM requires 128 refresh cycles every 2 ms (or 256 cycles in every 4 ms), the required refresh interval is less than or equal to 15.625 µs. Thus, the underlined values indicate the best refresh interval depending on CPU clock frequency. CYC0 and CYC1 are cleared to 0 during RESET (see Table 18).

Table 18. DRAM Refresh Intervals

			Time Interval				
CYC1	**CYC0**	**Insertion Interval**	**PHI: 10 MHz**	**8 MHz**	**6 MHz**	**4 MHz**	**2.5 MHz**
0	0	10 states	(1.0 µs)*	(1.25 µs)*	1.66 µs	2.5 µs	4.0 µs
0	1	20 states	(2.0 µs)*	(2.5 µs)*	3.3 µs	5.0 µs	8.0 µs
1	0	40 states	(4.0 µs)*	(5.0 µs)*	6.6 µs	10.0 µs	16.0 µs
1	1	80 states	(8.0 µs)*	(10.0 µs)*	13.3 µs	20.0 µs	32.0 µs

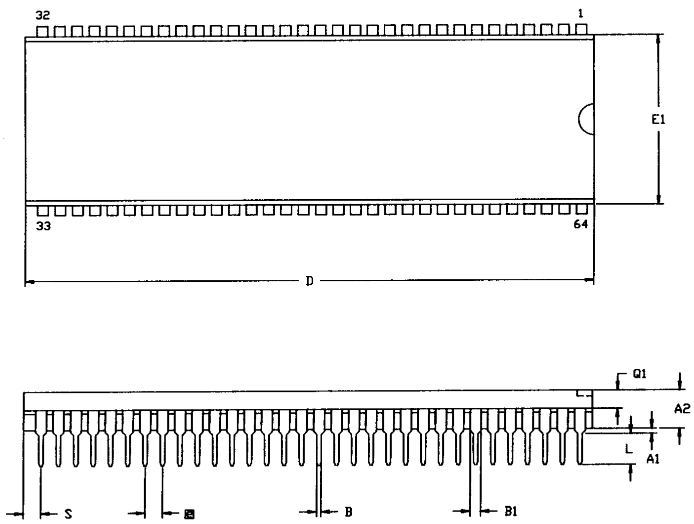
Note: *calculated interval.

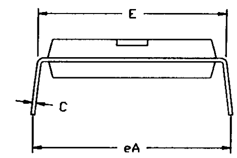
Refresh Control and Reset. After RESET, based on the initialized value of RCR, refresh cycles occur with an interval of 10 clock cycles and be 3 clock cycles in duration.

Dynamic RAM Refresh Operation

1. Refresh Cycle insertion is stopped when the CPU is in the following states:
   a. During RESET
   b. When the bus is released in response to $\overline{\text{BUSREQ}}$
   c. During SLEEP mode
   d. During $\overline{\text{WAIT}}$ states
2. Refresh cycles are suppressed when the bus is released in response to $\overline{\text{BUSREQ}}$. However, the refresh timer continues to operate. The time at which the first refresh cycle occurs after the Z8S180/Z8L180 reacquires the bus depends on the refresh timer. This cycle offers no timing relationship with the bus exchange.
3. Refresh cycles are suppressed during SLEEP mode. If a refresh cycle is requested during SLEEP mode, the refresh cycle request is internally latched (until replaced with the next refresh request). The latched refresh cycle is inserted at the end of the first machine cycle after SLEEP mode is exited. After this initial cycle, the time at which the next refresh cycle occurs depends on the refresh time and offers no relationship with the exit from SLEEP mode.
4. The refresh address is incremented by one for each successful refresh cycle, not for each refresh. Thus, independent of the number of missed refresh requests, each refresh bus cycle uses a refresh address incremented by one from that of the previous refresh bus cycles.

PACKAGE INFORMATION

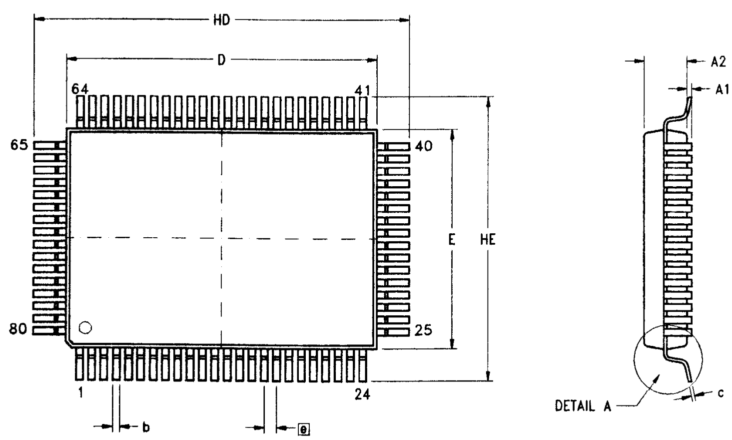




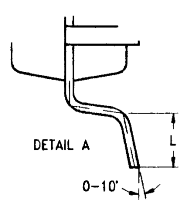
SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.38	1.07	.015	.042
A2	3.68	3.94	.145	.155
B	0.38	0.53	.015	.021
B1	0.94	1.09	.037	.043
C	0.23	0.38	.009	.015
D	57.40	58.17	2.260	2.290
E	18.80	19.30	.740	.760
E1	16.76	17.27	.660	.680
e	1.78 TYP		.070 TYP	
eA	19.30	20.32	.760	.800
L	3.18	3.81	.125	.150
Q1	1.65	1.91	.065	.075
S	1.02	1.78	.040	.070

CONTROLLING DIMENSIONS : INCH

Figure 85. 64-Pin DIP Package Diagram

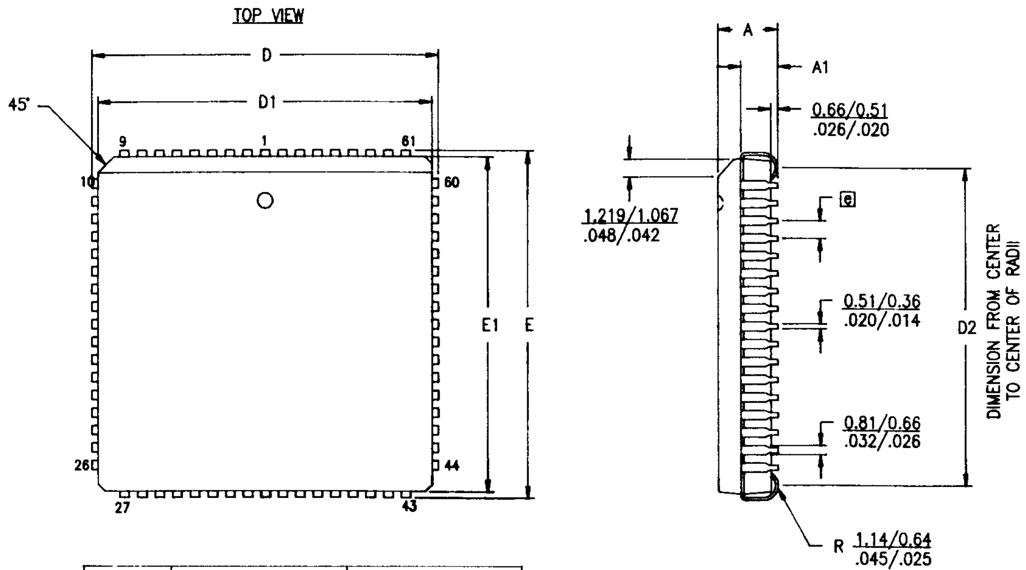


SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.10	0.30	.004	.012
A2	2.60	2.80	.102	.110
b	0.30	0.45	.012	.018
c	0.13	0.20	.005	.008
HD	23.70	24.15	.933	.951
D	19.90	20.10	.783	.791
HE	17.70	18.15	.697	.715
E	13.90	14.10	.547	.555
e	0.80 TYP		.0315 TYP	
L	0.70	1.10	.028	.043



NOTES:
1. CONTROLLING DIMENSIONS: MILLIMETER
2. MAX COPLANARITY: $\frac{.10}{.004}$

Figure 86. 80-Pin QFP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	4.32	4.57	.170	.180
A1	2.43	2.92	.095	.115
D/E	25.02	25.40	.985	1.000
D1/E1	24.13	24.33	.950	.958
D2	22.86	23.62	.900	.930
e	1.27 TYP		.050 TYP	

NOTES:

1. CONTROLLING DIMENSIONS : INCH
2. LEADS ARE COPLANAR WITHIN .004 IN RANGE.
3. DIMENSION : MM / INCH

Figure 87. 68-Pin PLCC Package Diagram

ORDERING INFORMATION

Codes	
Speed	10 = 10 MHz 20 = 20 MHz 33 = 33 MHz
Package	P = 60-Pin Plastic DIP V = 68-Pin PLCC F = 80-Pin QFP
Temperature	S = 0°C to +70°C E = –40°C to +85°C
Environmental	C = Plastic Standard

For fast results, contact your local ZiLOG sales office for assistance in ordering the part(s) required.

Example:

Z 8S180 10 P S C is a Z8S180 10-MHz 60-Pin DIP, 0° to +70°C, Plastic Standard Flow

- C — Environmental Flow
- S — Temperature
- P — Package
- 10 — Speed
- 8S180 — Product Number
- Z — ZiLOG Prefix

Pre-Characterization Product

The product represented by this document is newly introduced and ZiLOG has not completed the full characterization of the product. The document states what ZiLOG knows about this product at this time, but additional features or non-conformance with some aspects of the document may be found, either by ZiLOG or its customers in the course of further application and characterization work. In addition, ZiLOG cautions that delivery may be uncertain at times, due to start-up yield issues.

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